

What is claimed is:

1. A wet cleaning or wet etch facility, comprising:
 - at least one chemical bath comprising a vessel having an open top, and a respective chemical contained in the vessel, whereby wafers can be dipped into the chemical contained in the vessel;
 - a drying unit disposed downstream of said at least one chemical bath in the facility and operable to dry wafers;
 - a robot arm having a working envelope encompassing said chemical baths and said drying unit so as to be operable to transport wafers to said at least one chemical bath and to said drying unit in sequence;
 - a bubble-detecting sensor operatively associated with each said at least one chemical bath so as to sense the amount of bubbles produced in the chemical of said bath and operative to generate signals indicative of said amount of bubbles; and
 - a controller to which said bubble-detecting sensor is operatively connected so as to receive said signals.
2. The facility according to claim 1, wherein said bubble-detecting sensor comprises a vibration sensor operative to generate a signal indicative of the amount said chemical is vibrating.
3. The facility according to claim 1, wherein said bubble-detecting

sensor comprises an optical sensor operative to generate a signal indicative of the color of said chemical.

4. The facility according to claim 1, wherein said bubble-detecting sensor comprises a photo sensor having a light-transmitter and a light receptor.

5. The facility according to claim 1, wherein each said at least one chemical bath comprises an internal chemical tank that contains the chemical, and an external chemical tank positioned relative to said internal chemical tank so as to receive chemicals that overflow out of the internal chemical tank, and further comprising a chemical circulating line extending from a bottom portion of said external chemical tank to an upper portion of said internal chemical tank and through which the chemical is circulated from said external chemical tank back into said internal chemical tank, and a second bubble-detecting sensor operatively associated with said chemical circulating line so as to sense the amount of bubbles entrained in the chemical within said chemical circulating line and operative to generate signals indicative thereof, said controller being operatively connected to said second bubble-detecting so as to receive the signals generated thereby.

6. The facility according to claim 1, wherein each said at least one chemical bath comprises a vessel having transparent side walls.

7. The facility according to claim 5, wherein each said at least one chemical bath comprises a vessel having transparent side walls.
8. The facility according to claim 5, wherein said chemical circulating line is transparent.
9. The facility according to claim 7, wherein said chemical circulating line is transparent.
10. A wet cleaning or wet etch facility, comprising:
 - at least one chemical bath comprising an internal chemical tank, a respective chemical contained in the internal chemical tank, and an external chemical tank positioned relative to said internal chemical tank so as to receive chemicals that overflow out of the internal chemical tank, whereby a source of contamination can be removed by the chemical from the surface of a wafer by dipping the wafer into the chemical contained in the internal chemical tank;
 - a drying unit disposed downstream of said at least one chemical bath in the facility and operable to dry wafers;
 - a robot arm having a working envelope encompassing said chemical baths and said drying unit so as to be operable to transport wafers to said at least one chemical bath and to said drying unit in sequence;

a chemical circulating line extending from a bottom portion of said external chemical tank to an upper portion of said internal chemical tank and through which the chemical is circulated from said external chemical tank back into said internal chemical tank;

a bubble-detecting sensor operatively associated with said chemical circulating line so as to sense the amount of bubbles entrained in the chemical within said chemical circulating line and operative to generate signals indicative thereof; and

a controller operatively connected to said bubble-detecting sensor so as to receive said signals therefrom.

11. The facility according to claim 10, wherein said bubble-detecting sensor comprises a vibration sensor operative to generate a signal indicative of the amount said chemical is vibrating.

12. The facility according to claim 10, wherein said bubble-detecting sensor comprises an optical sensor operative to generate a signal indicative of the color of said chemical.

13. The facility according to claim 10, wherein said bubble-detecting sensor comprises a photo sensor having a light-transmitter and a light receptor.

14. The facility according to claim 10, wherein said chemical circulating line is transparent.